ABSTRACT

An optoelectronic subassembly for optoelectronic modules includes a supporting substrate with an optoelectronic device mounted on a mounting surface. A supporting structure includes a trench for mounting the subassembly and a lens assembly. Four offset arms are provided each including a substrate-mounting portion, a supporting-structure-mounting portion, and a linking portion. The substrate-mounting portion and the supporting-structure-mounting portion have parallel surfaces with the linking portion extending at an angle therebetween. The arms include deformable material for allowing small changes in the angle. One of the parallel surfaces of each of the offset arms is mounted on either the mounting surface or an opposed surface of the supporting substrate and the other of the parallel surfaces is mounted on the support structure with the substrate suspended in the trench. The linking portion of the arms is then deformed to align the optoelectronic device with the lens assembly.